COLD MOUNTING CONSUMABLES



MLP-CM1

Code	Description	Package
MLP-CM1	1. fast curing speed, good transparency, low viscosity, high strength 2. for metallographic samples without heating, pressure and mounting 3. curing time: 25°C, 25min 4. usage: mix cold mounting resin and curing liquid at 10:8	cold mounting resin: 1000g curing agent: 800ml
MLP-CM3	1. fast curing speed, good transparency 2. for samples which can not be heated, like PCB, SMT and other micro-slice samples 3. curing time: 25°C, 1h 4. usage: mix resin liquid and curing liquid at 2:1	resin liquid: 1000ml curing agent: 500ml
MLP-CM4	1. low viscosity, good permeability, high transparency 2. for samples which can not be heated, like PCB, SMT and other micro-slice samples 3. curing time: 25°C, 3~4h 4. usage: mix resin liquid and curing liquid at 2:1	resin liquid: 1000ml curing agent: 500ml
MLP-CM5	1. low heat generation, low shrinkage, high permeability, high transparency 2. for temperature-sensitive samples, like PCB, SMT and other micro-slice samples 3. curing time: 25°C, 20~24h 4. usage: mix resin liquid and curing liquid at 3:1	resin liquid: 1000ml curing agent: 300ml
MLP-CM7	1. UV curing adhesive, high transparency, good fluidity 2. for scenarios that require rapid embedding, like PCB, SMT and other micro-slice samples 3. curing time: used with light curing machine, curing time less than 10min 4. usage: use directly	UV adhesive: 1000ml